

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.43729	100.0	6.3
Subtotal				0.43729	100	6.3
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.02829	100.0	0.40755
	Pure metal	Aluminium (Al)	7429-90-5	0.16242	100.0	2.34
	Pure metal	Aluminium (Al)	7429-90-5	0.02829	100.0	0.40755
Subtotal				0.219	300	3.1551
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.73526	100.0	25
Subtotal				1.73526	100	25
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02332	0.04	0.336
	Copper alloy	Iron (Fe)	7439-89-6	0.0583	0.1	0.84
	Copper alloy	Copper (Cu)	7440-50-8	58.22316	99.86	838.824
Subtotal				58.30478	100	840
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.39677	8.7	48.9375
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.24694	16.0	90
	Filler	Silica fused	60676-86-0	29.28254	75.0	421.875
	Carbon Black	Carbon black	1333-86-4	0.11713	0.3	1.6875
Subtotal				39.04338	100	562.5
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.01301	5.0	0.1875
	Lead alloy	Silver (Ag)	7440-22-4	0.00651	2.5	0.09375
	Lead alloy	Lead (Pb)	7439-92-1	0.24077	92.5	3.46875
Subtotal				0.26029	100	3.75
Total				100	100	1440.7051

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.